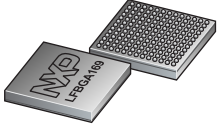


# SOT2239-1

LFBGA169, low-profile fine-pitch ball grid array package, 169 terminals, 0.5 mm pitch, 7 mm x 7 mm x 1.11 mm body

13 March 2025

Package information



## 1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA169
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	28-02-2024
Manufacturer package code	98ASA02164D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	6.85	7	7.15	mm
package width	6.85	7	7.15	mm
seated height	-	1.11	1.23	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	169	-	



LFBGA169, low-profile fine-pitch ball grid array package, 169 terminals, 0.5 mm pitch, 7 mm x 7 mm x 1.11 mm body

2 Package outline

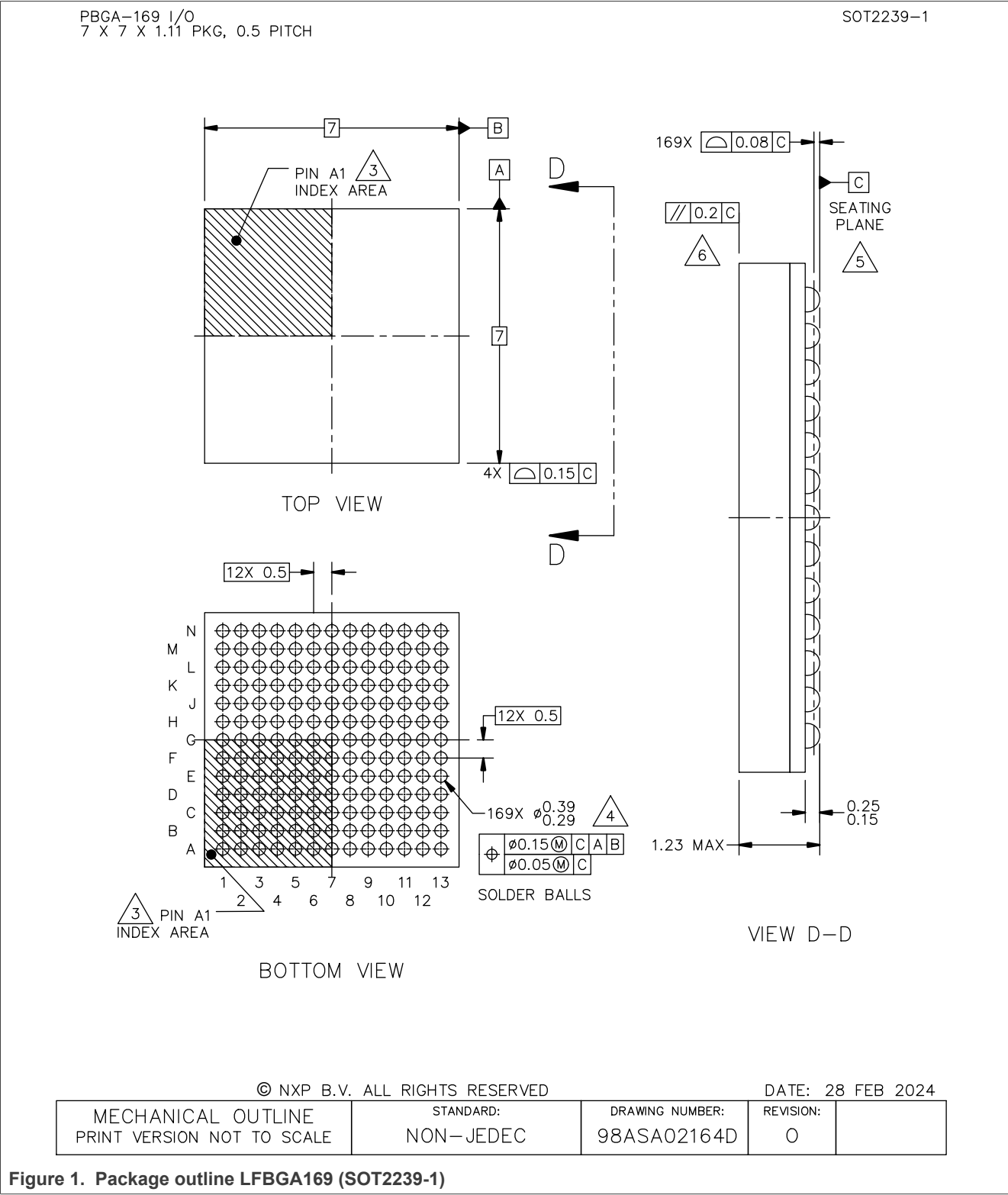
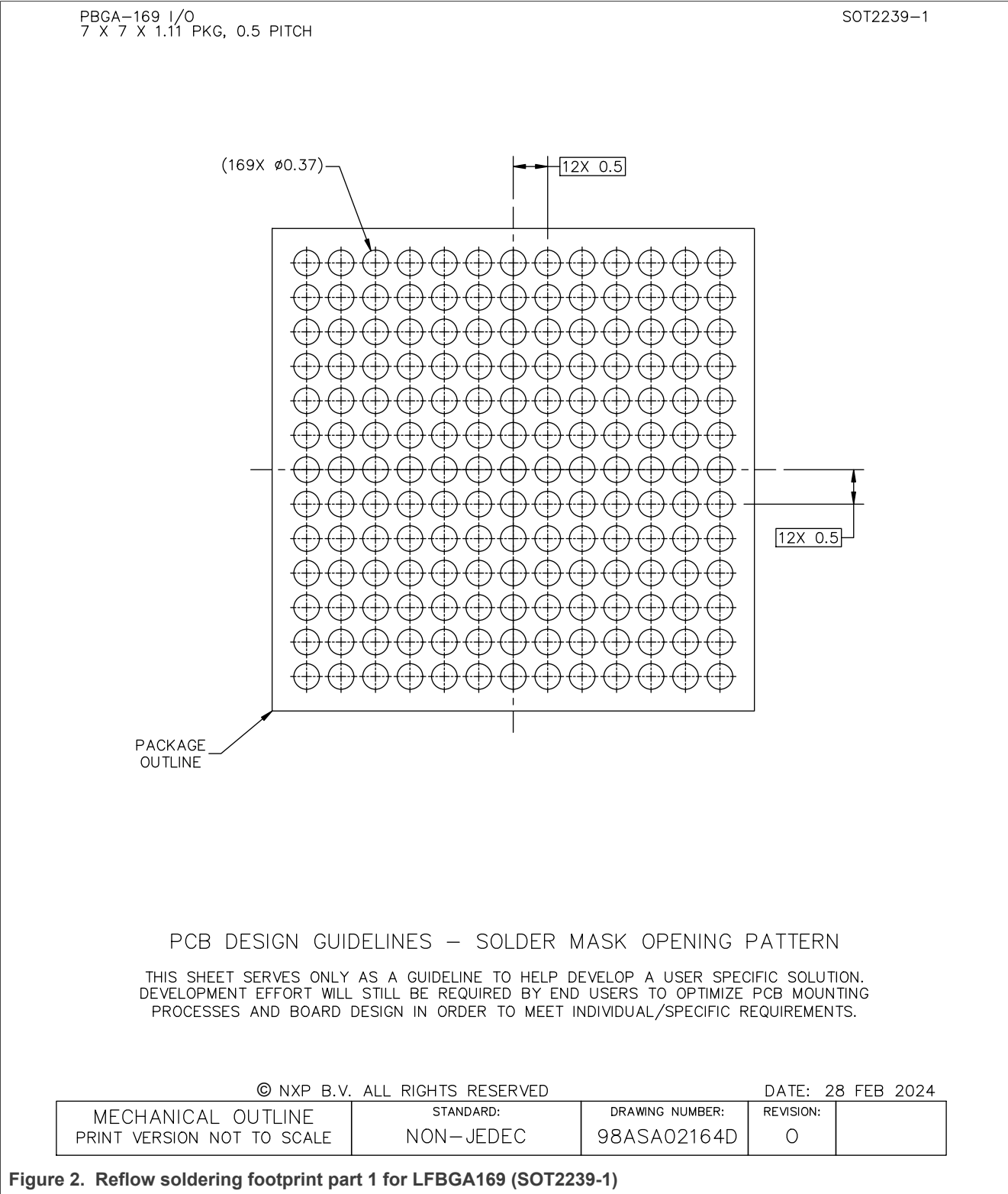


Figure 1. Package outline LFBGA169 (SOT2239-1)

LFBGA169, low-profile fine-pitch ball grid array package, 169 terminals, 0.5 mm pitch, 7 mm x 7 mm x 1.11 mm body

3 Soldering



LFBGA169, low-profile fine-pitch ball grid array package, 169 terminals, 0.5 mm pitch, 7 mm x 7 mm x 1.11 mm body

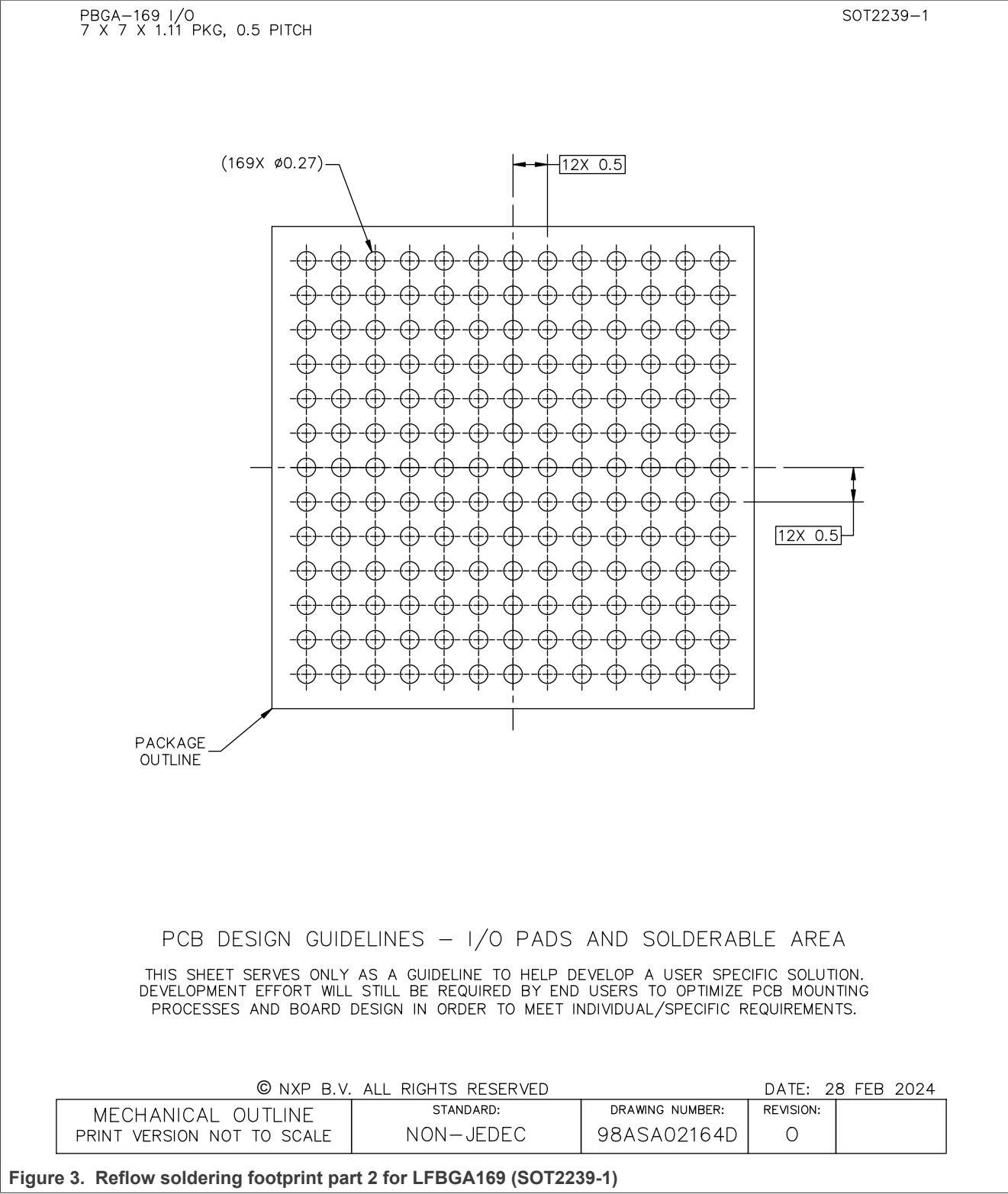


Figure 3. Reflow soldering footprint part 2 for LFBGA169 (SOT2239-1)

LFBGA169, low-profile fine-pitch ball grid array package, 169 terminals, 0.5 mm pitch, 7 mm x 7 mm x 1.11 mm body

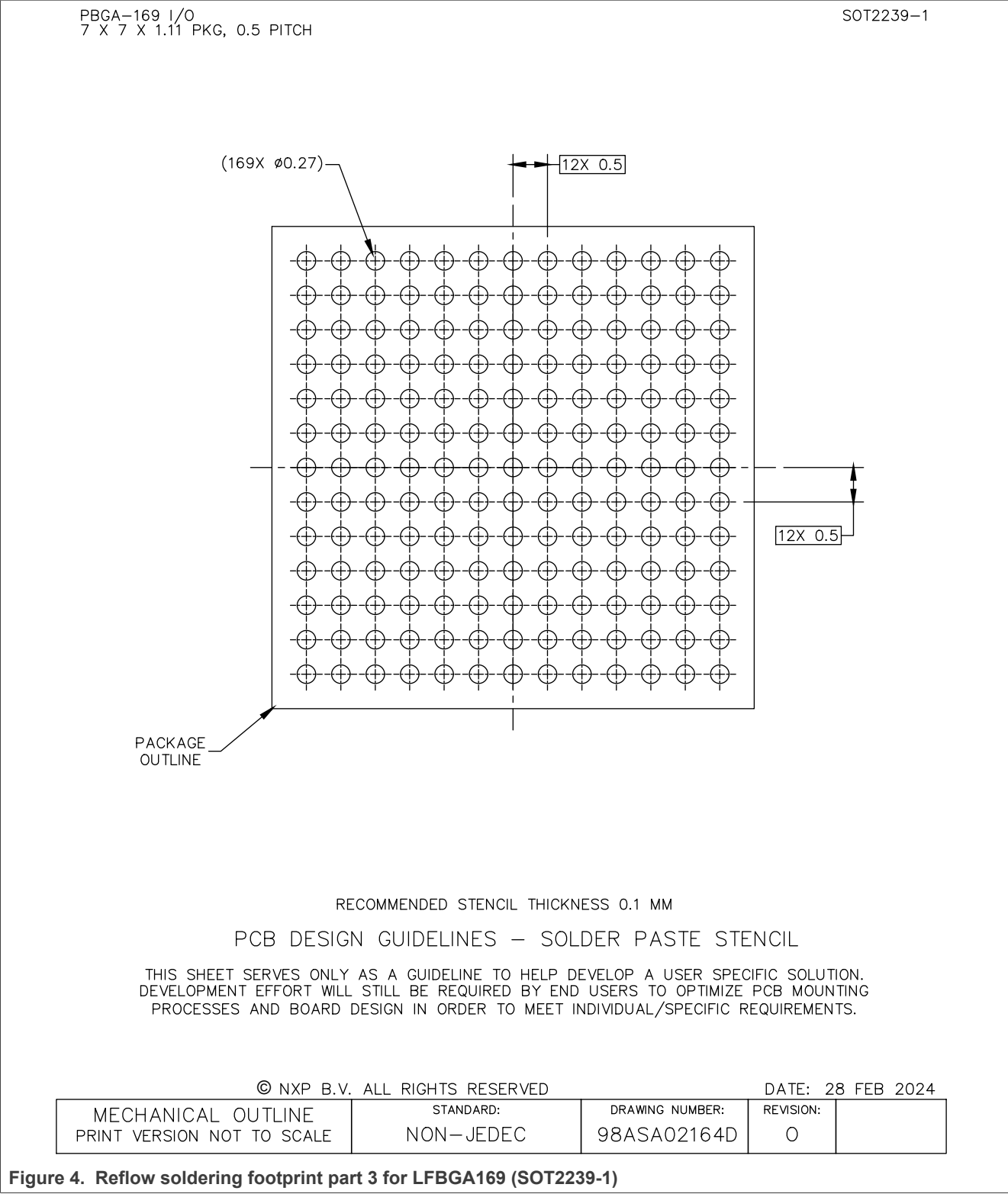


Figure 4. Reflow soldering footprint part 3 for LFBGA169 (SOT2239-1)

LFBGA169, low-profile fine-pitch ball grid array package, 169 terminals, 0.5 mm pitch, 7 mm x 7 mm x 1.11 mm body

PBGA-169 I/O  
7 X 7 X 1.11 PKG, 0.5 PITCH

SOT2239-1

NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
- 4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
- 5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA02164D	REVISION: 0	

Figure 5. Package outline note LFBGA169 (SOT2239-1)

## 4 Legal information

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LFBGA169, low-profile fine-pitch ball grid array package, 169 terminals, 0.5 mm pitch, 7 mm x 7 mm x 1.11 mm body

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